

Part Number: Applicable to ASF, ASL, AST, ASW, AWG-series.
Product Name: GaAs Amplifier
Package Type: SOT363

Package Elements	Constituents	CAS No.	Weight (mg)	Weight %
Active Semiconductor Die	GaAs	1303-00-0	0.153	85
	Au	7440-57-5	0.027	15
Leadframe	Cu	7440-50-8	2.93612	97.1
	Fe	7439-89-6	0.06652	2.2
	P	7723-14-0	0.00151	0.05
	Zn	7440-66-6	0.00302	0.1
	Pb	7439-92-1	0.00030	0.01
	Ag	7440-22-4	0.01633	0.54
Leadframe Plating	Sn	7440-31-5	0.10426	99.99
	Mics., not to declare	-	0.00001	0.01
Epoxy Molding Compound	Epoxy Resin A	Trade Secret	0.237514	6.5
	Epoxy Resin B	29690-82-2	0.073081	2
	Phenolic Resin	Trade Secret	0.073081	2
	Silica (Amorphous)	60676-86-0	3.252113	89
	Carbon Black	1333-86-4	0.01827	0.5
Epoxy Resin	Ag	7440-22-4	0.0289	83
	Epoxy Resin	Trade Secret	0.0043	12
	Dicyandiamide	461-58-5	0.0009	2.5
	Polymeric material	Trade Secret	0.0009	2.5
Gold Wire	Au	7440-57-5	0.06584	99
	Mics., not to declare	-	0.00067	1
Total			7.064	100

This information sheet is to declare all substances intentionally added in our SOT363 semiconductor products. Total weight of the package varies depending on active die size. The material data is evidenced by written declaration from our packaging company. The products listed above DO NOT CONTAIN intentionally added hazardous materials such as cadmium (Cd), mercury (Hg), hexavalent chromium (Cr⁶⁺), polybrominated biphenyls (PBBs), polybrominated diphenylethers (PBDEs), bis(2-ethylhexyl) phthalate (DEHP), butyl benzyl phthalate (BBP), dibutyl phthalate (DBP), and diisobutyl phthalate (DIBP) except for 0.01 wt.% of lead (Pb), which **COMPLY with the RoHS3 Directive 2015/863/EU**. For further information, contact our Sales Department at sales@asb.co.kr.



Authorized Signature, ASB Inc.

This data is based on information provided by our suppliers and we do not validate it by measurement. ASB Inc. assumes no responsibility in connection with any use of this information. The information is subject to change without notice.

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